NTLJF3118N

Power MOSFET and Schottky Diode

20 V, 4.6 A, μCool™ N−Channel, with 2.0 A Schottky Barrier Diode, 2x2 mm WDFN Package

ON Semiconductor®

http://onsemi.com

Features

- WDFN 2x2 mm Package Provides Exposed Drain Pad for Excellent Thermal Conduction
- Footprint Same as SC−88 Package
- 1.8 V V_{GS} Rated $R_{DS(on)}$
- Low Profile (< 0.8 mm) for Easy Fit in Thin Environments
- Low V_F 2 A Schottky Diode
- This is a Pb−Free Device

Applications

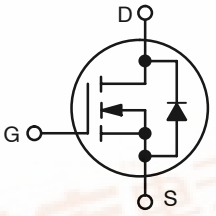
- DC−DC Boost/Buck Converter
- Low Voltage Hard Disk DC Power Source

MOSFET

$V_{(BR)DSS}$	$R_{DS(on)}$ Max	I_D Max
20 V	65 mΩ @ 4.5 V	3.8 A
	75 mΩ @ 2.5 V	2.0 A
	120 mΩ @ 1.8 V	1.7 A

SCHOTTKY DIODE

V_R Max	V_F Typ	I_F Max
20 V	0.41 V	2.0 A

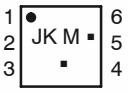


N−CHANNEL MOSFET

SCHOTTKY DIODE

WDFN6
CASE 506AN

MARKING DIAGRAM



JK = Specific Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

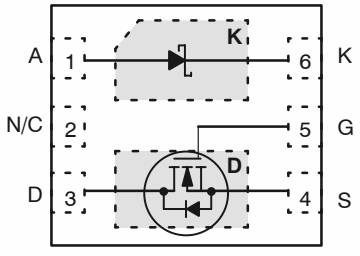
MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain−to−Source Voltage			V_{DSS}	20	V
Gate−to−Source Voltage			V_{GS}	±12	V
Continuous Drain Current (Note 1)	Steady State	T_A = 25°C	I_D	3.8	A
		T_A = 85°C		2.8	
	t ≤ 5 s	T_A = 25°C		4.6	
Power Dissipation (Note 1)	Steady State	T_A = 25°C	P_D	1.5	W
	t ≤ 5 s			2.2	
Continuous Drain Current (Note 2)	Steady State	T_A = 25°C	I_D	2.6	A
		T_A = 85°C		1.9	
Power Dissipation (Note 2)		T_A = 25°C	P_D	0.7	
Pulsed Drain Current	t_p = 10 μs		I_{DM}	18	A
Operating Junction and Storage Temperature			T_J, T_{STG}	−55 to 150	°C
Source Current (Body Diode)			I_S	1.8	A
Lead Temperature for Soldering Purposes (1/8″ from case for 10 s)			T_L	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface Mounted on FR4 Board using 2 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
2. Surface Mounted on FR4 Board using the minimum recommended pad size.

PIN CONNECTIONS



(Top View)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

SCHOTTKY DIODE MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	20	V
DC Blocking Voltage	V_R	20	V
Average Rectified Forward Current	I_F	2.0	A

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction−to−Ambient − Steady State (Note 3)	$R_{\theta JA}$	83	°C/W
Junction−to−Ambient − t ≤ 5 s (Note 3)	$R_{\theta JA}$	58	
Junction−to−Ambient − Steady State Min Pad (Note 4)	$R_{\theta JA}$	177	

3. Surface Mounted on FR4 Board using 2 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
4. Surface Mounted on FR4 Board using the minimum recommended pad size.

MOSFET ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions		Min	Typ	Max	Unit
OFF CHARACTERISTICS							
Drain−to−Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 250 μA		20			V
Drain−to−Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	I_D = 250 μA, Ref to 25°C			10.4		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 16 V, V_{GS} = 0 V	T_J = 25°C			1.0	μA
			T_J = 85°C			10	
Gate−to−Source Leakage Current	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±8.0 V				±100	nA
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = 250 μA		0.4	0.7	1.0	V
Gate Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$				−3.0		mV/°C
Drain−to−Source On−Resistance	$R_{DS(on)}$	V_{GS} = 4.5, I_D = 3.8 A			37	65	mΩ
		V_{GS} = 2.5, I_D = 2.0 A			46	75	
		V_{GS} = 1.8, I_D = 1.7 A			65	120	
Forward Transconductance	g_{FS}	V_{DS} = 10 V, I_D =1.7 A			4.2		S
CHARGES, CAPACITANCES AND GATE RESISTANCE							
Input Capacitance	C_{ISS}	V_{GS} = 0 V, f = 1 MHz, V_{DS} = 10 V			271		pF
Output Capacitance	C_{OSS}				72		
Reverse Transfer Capacitance	C_{RSS}				43		
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = 4.5 V, V_{DS} = 10 V, I_D = 3.8 A			3.7		nC
Threshold Gate Charge	$Q_{G(TH)}$				0.3		
Gate−to−Source Charge	Q_{GS}				0.6		
Gate−to−Drain Charge	Q_{GD}				1.0		
SWITCHING CHARACTERISTICS (Note 6)							
Turn−On Delay Time	$t_{d(ON)}$	V_{GS} = 4.5 V, V_{DD} = 16 V, I_D = 1.0 A, R_G = 2.0 Ω			3.8		ns
Rise Time	t_r				4.7		
Turn−Off Delay Time	$t_{d(OFF)}$				11.1		
Fall Time	t_f				5.8		
DRAIN−SOURCE DIODE CHARACTERISTICS							
Forward Diode Voltage	V_{SD}	V_{GS} = 0 V, IS =1.0 A	T_J = 25°C		0.69	1.0	V
Reverse Recovery Time	t_{RR}	V_{GS} = 0 V, d_{ISD}/d_t = 100 A/μs, I_S = 1.0 A			10.2		ns

5. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
6. Switching characteristics are independent of operating junction temperatures.

SCHOTTKY DIODE ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Maximum Instantaneous Forward Voltage	V_F	I_F = 0.1 A		0.26	0.35	V
		I_F = 1.0 A		0.35	0.42	
		I_F = 2.0 A		0.41	0.52	
Maximum Instantaneous Reverse Current	I_R	V_R = 20 V		0.20	5.0	mA
		V_R = 10 V		0.045	1.0	

SCHOTTKY DIODE ELECTRICAL CHARACTERISTICS (T_J = 85°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Maximum Instantaneous Forward Voltage	V_F	I_F = 0.1 A		0.18		V
		I_F = 1.0 A		0.29		
		I_F = 2.0 A		0.36		
Maximum Instantaneous Reverse Current	I_R	V_R = 20 V		4.9		mA
		V_R = 10 V		1.6		

SCHOTTKY DIODE ELECTRICAL CHARACTERISTICS (T_J = 125°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Maximum Instantaneous Forward Voltage	V_F	I_F = 0.1 A		0.13		V
		I_F = 1.0 A		0.25		
		I_F = 2.0 A		0.33		
Maximum Instantaneous Reverse Current	I_R	V_R = 20 V		42		mA
		V_R = 10 V		13		

SCHOTTKY DIODE ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Capacitance	C	V_R = 5.0 V, f = 1.0 MHz		52.3		pF

ORDERING INFORMATION

Device	Package	Shipping†
NTLJF3118NTAG	WDFN6 (Pb−Free)	3000 / Tape & Reel
NTLJF3118NTBG	WDFN6 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL N−CHANNEL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

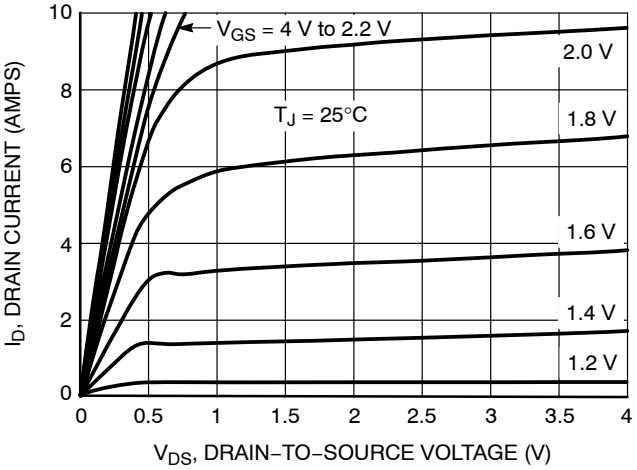


Figure 1. On−Region Characteristics

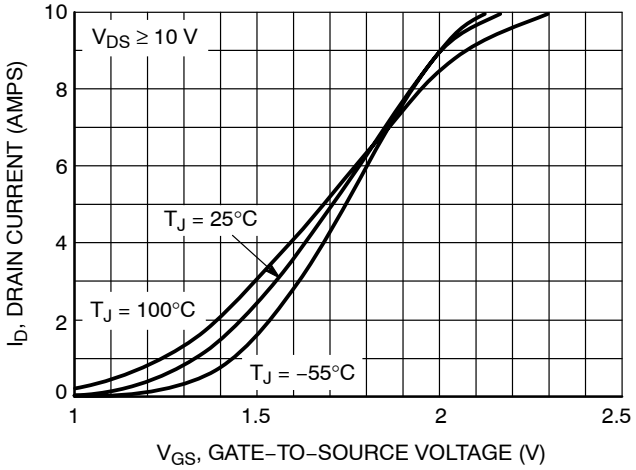


Figure 2. Transfer Characteristics

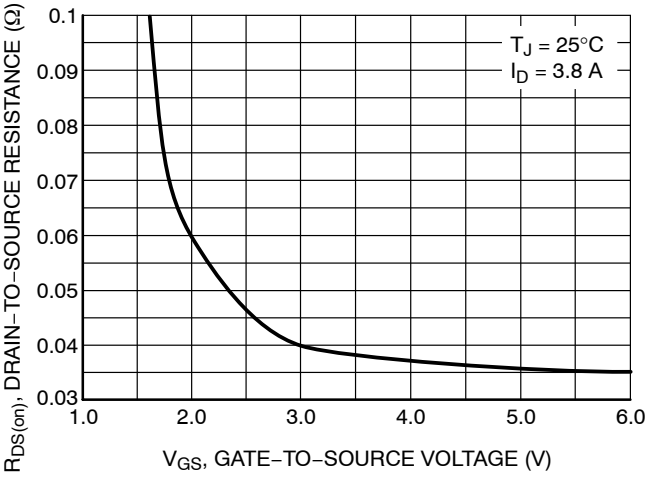


Figure 3. On−Resistance versus Drain Current

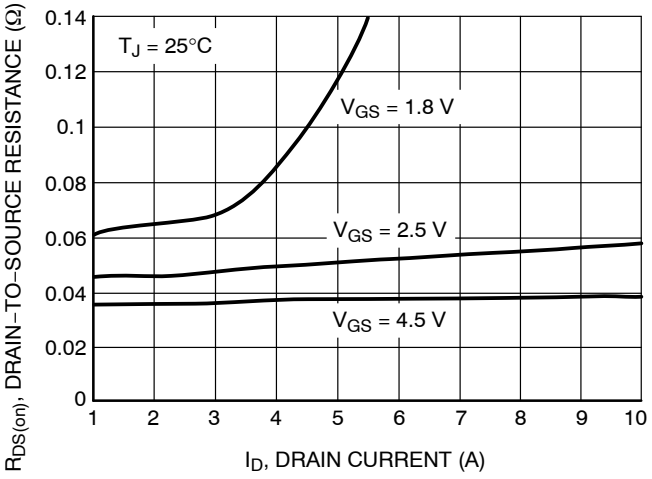


Figure 4. On−Resistance versus Drain Current and Gate Voltage

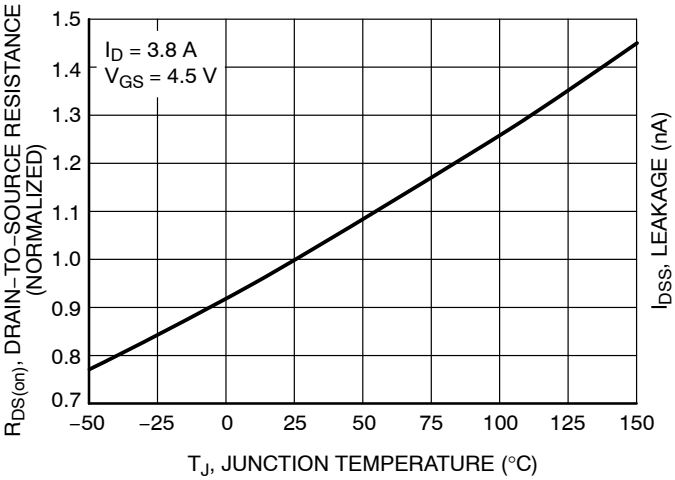


Figure 5. On−Resistance Variation with Temperature

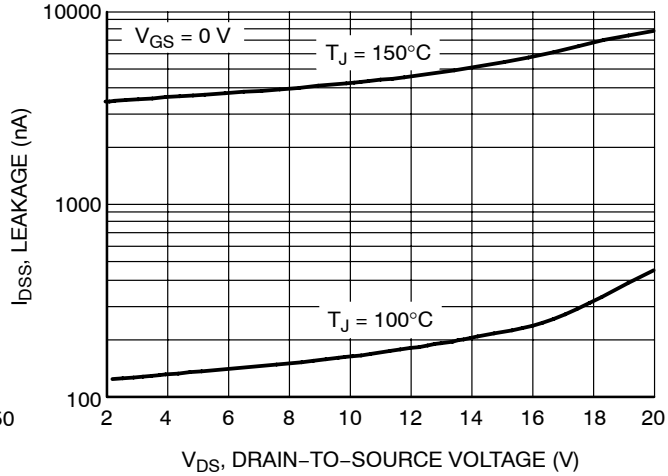


Figure 6. Drain−to−Source Leakage Current versus Voltage

TYPICAL N−CHANNEL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

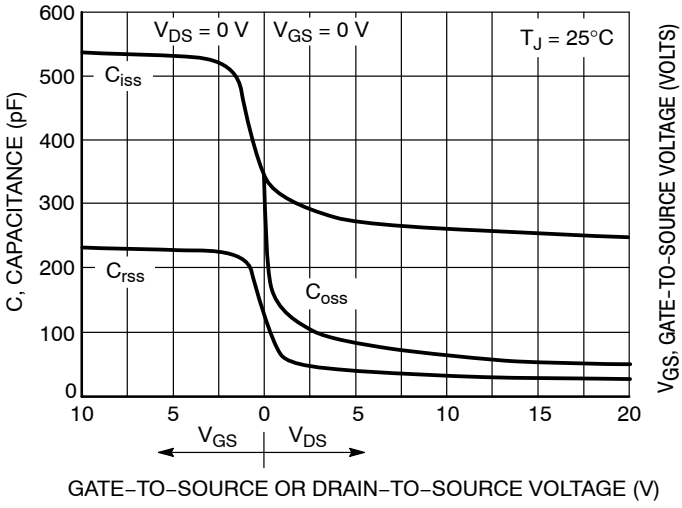


Figure 7. Capacitance Variation

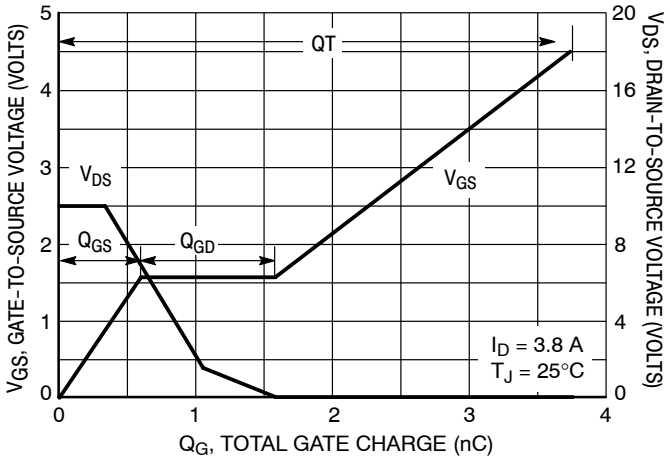


Figure 8. Gate−To−Source and Drain−To−Source Voltage versus Total Charge

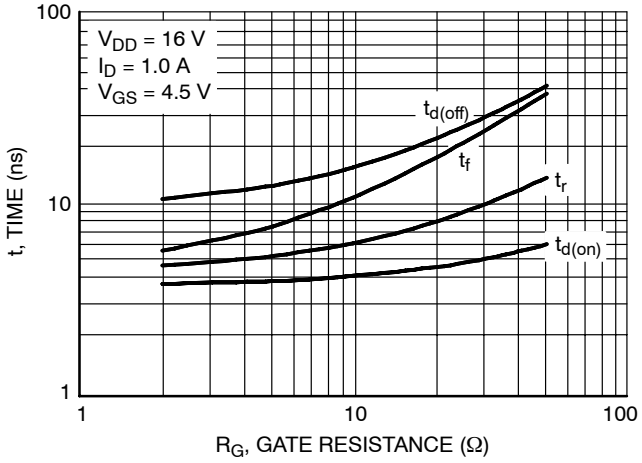


Figure 9. Resistive Switching Time Variation versus Gate Resistance

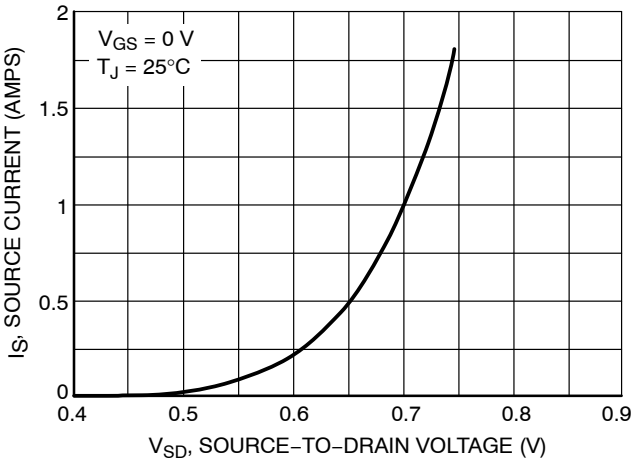


Figure 10. Diode Forward Voltage versus Current

TYPICAL SCHOTTKY PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

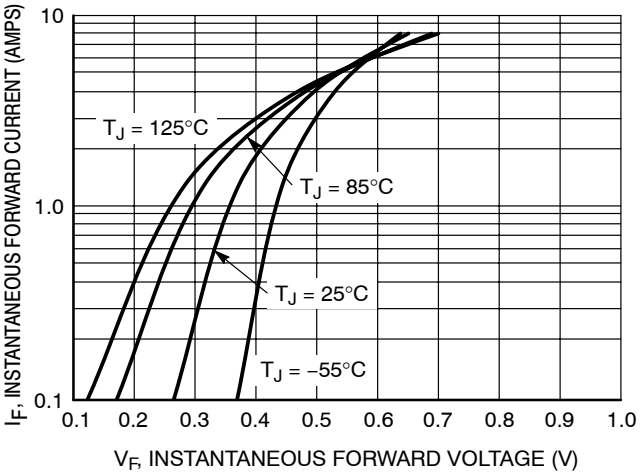


Figure 11. Typical Forward Voltage

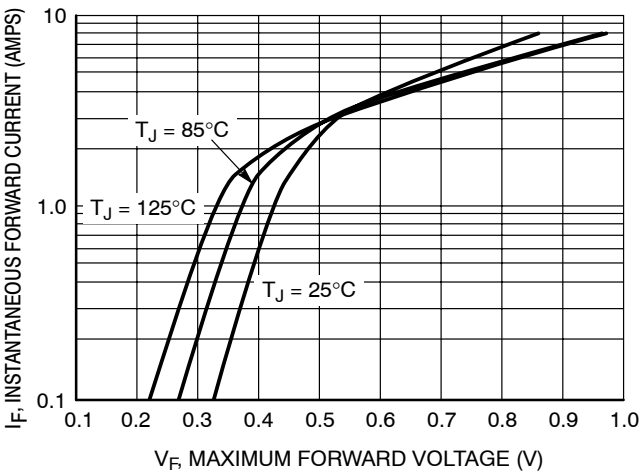


Figure 12. Maximum Forward Voltage

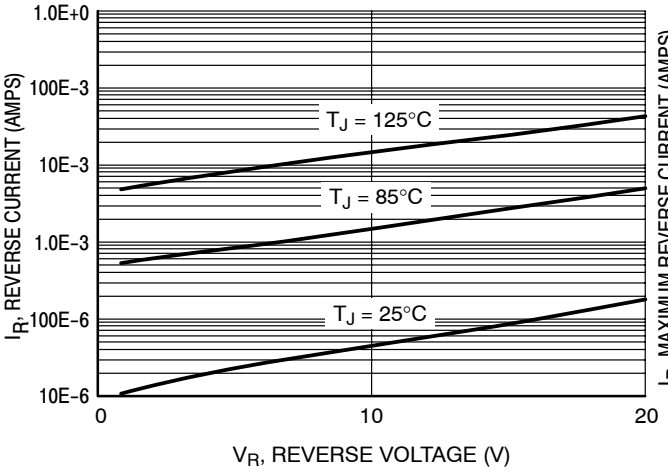


Figure 13. Typical Reverse Current

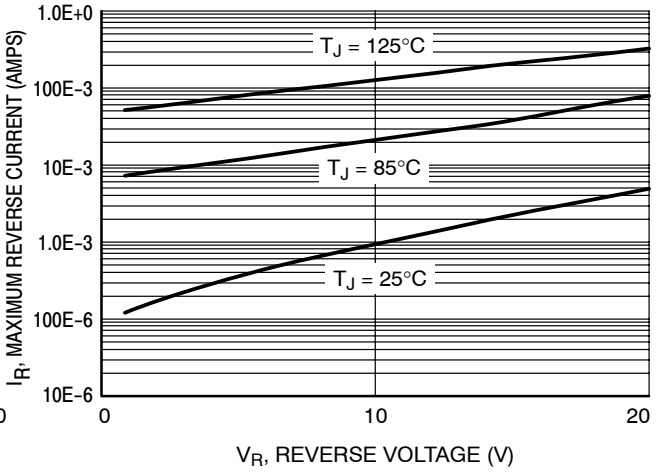
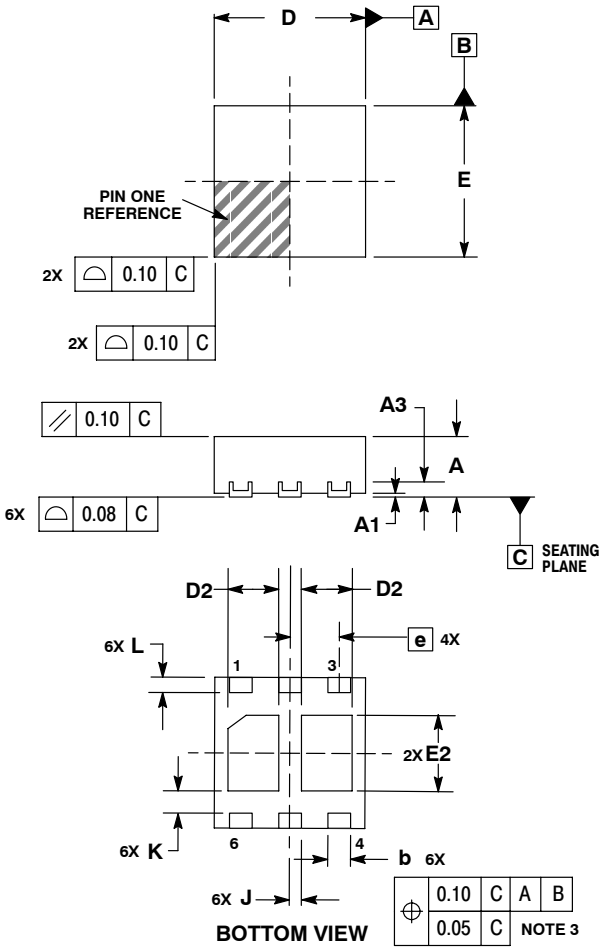


Figure 14. Maximum Reverse Current

NTLJF3118N

PACKAGE DIMENSIONS

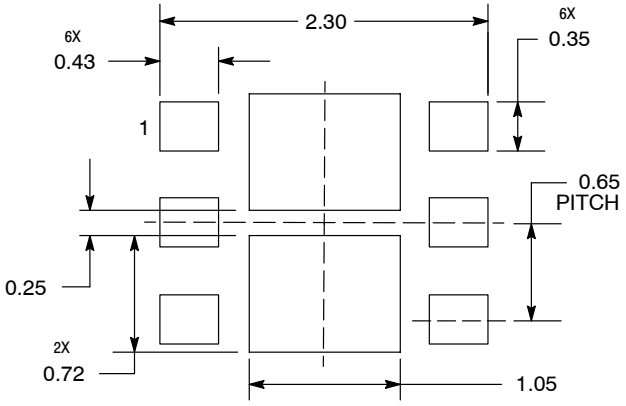
WDFN6, 2x2
CASE 506AN−01
ISSUE B



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.25	0.35
D	2.00 BSC	
D2	0.57	0.77
E	2.00 BSC	
E2	0.90	1.10
e	0.65 BSC	
K	0.25 REF	
L	0.20	0.30
J	0.15 REF	

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PUBLICATION ORDERING INFORMATION

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